

CLAIMS

1. A metal base circuit substrate for an optical device comprising a metal base substrate made from aluminum or aluminum alloy that supports an electric circuit via an insulation layer, wherein said insulation layer is formed from a transparent cross-linked silicone body, and said electric circuit is formed directly on said insulation layer.
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2. The metal base circuit substrate for an optical device according to Claim 1, wherein said insulation layer has a thickness not exceeding 10 μm .
3. The metal base circuit substrate for an optical device according to Claim 1, wherein a dielectric constant of said cross-linked silicone body does not exceed 4.0.
- 10 4. The metal base circuit substrate for an optical device according to Claim 1, wherein said circuit is formed either by etching a conductive layer formed in said insulation layer by electrolytic or non-electrolytic plating, or by printing said circuit on said insulation layer with the use of an electroconductive ink.
- 15 5. A method of manufacturing a metal base circuit substrate for an optical device comprising the steps of:
 - a) applying a cross-linkable silicone onto the surface of a metal base substrate made from aluminum or aluminum alloy,
 - b) cross-linking said silicone, thereby forming an insulation layer from the transparent cross-linked silicone body; and then
 - 20 c) forming an electric circuit directly on said insulation layer either by (i) forming a conductive layer by electrolytic or non-electrolytic plating with subsequent etching, or (ii) by printing with a conductive ink.